Panasonic

Zener Diode DZ2711000L

DZ2711000L Silicon epitaxial planar type

For constant voltage / For surge absorption circuit DZ2S110 in SSSMini2 type package

Features

- · Excellent rising characteristics of zener current Iz
- Low zener operating resistance Rz
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: PJ

Packaging

Embossed type (Thermo-compression sealing) 10 000 pcs / reel (standard)

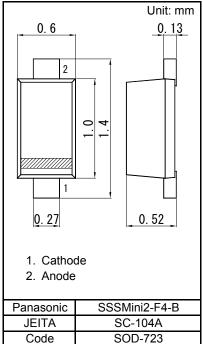
■ Absolute Maximum Ratings Ta = 25 °C

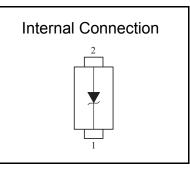
Parameter	Symbol	Rating	Unit
Repetitive peak forward current	IFRM	200	mA
Total power dissipation ^{*1}	PT	120	mW
Electrostatic discharge *2	ESD	±8	kV
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Stanges torge and use	Tata	EE to 1450	°C

 Storage temperature
 Tstg
 -55 to +150
 °(

 Note) *1: Mounted on glass epoxy print board. (45 mm x 45 mm x 1 mm)
 Solder in (0.4 mm x 0.3 mm)

*2: Test method: IEC61000 4 2(C = 150 pF, R = 330 Ω , Contact discharge: 10 times)





Tvn

Max

1.0

11.55

30

60

0.05

Unit

V

v

Ω

Ω

μA

■ Electrical Characteristics Ta = 25 °C ± 3 °C						
Parameter	Symbol	Conditions	Min	Т		
Forward voltage	VF	IF = 10 mA				
Zener voltage ^{*1, *2}	VZ	IZ = 5 mA	10.45			

RZ

RZK

IR

Temperature coefficient of zener voltage *3 SZ IZ = 5 mA 8.3 mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

IZ = 5 mA

IZ = 0.5 mA

VR = 8.0 V

2. Absolute frequency of input and output is 5 MHz.

3. *1 The temperature must be controlled 25 °C for VZ mesurement.

VZ value measured at other temperature must be adjusted to VZ (25 °C)

*2 VZ guaranted 20 ms after current flow.

*3 Tj = 25 °C to 150 °C

Zener operating resistance

Reverse current

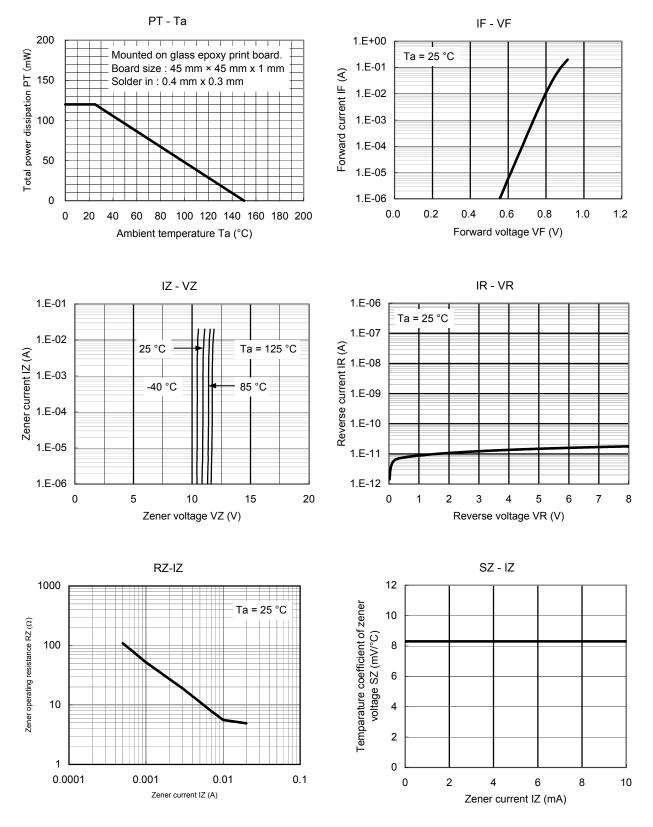
Zener rise operating resistance



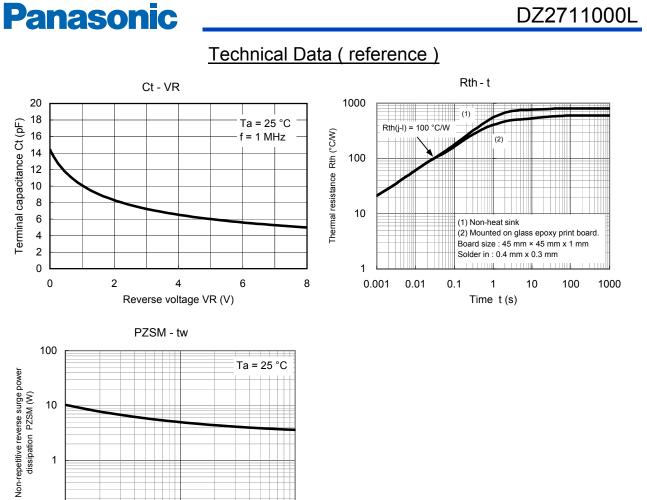


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10000

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0.1 100

1000

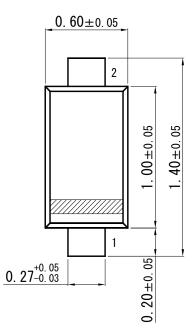
Pulse width tw (µs)

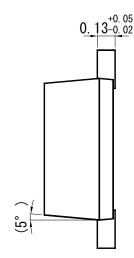


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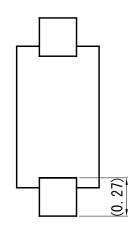
Unit: mm

SSSMini2-F4-B

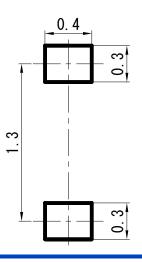




 $\begin{array}{c|c} 0 & to & 0.05 \\ \hline 0.52 \pm 0.03 \\ \hline 0.52 \pm 0.03 \\ \hline \end{array}$



■ Land Pattern (Reference) (Unit: mm)



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